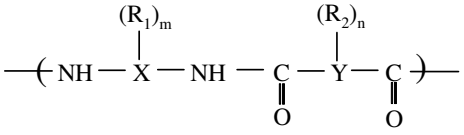
POLYAMIDE RESIN, POSITIVE-WORKING PHOTOSENSITIVE RESIN COMPOSITION, METHOD FOR PRODUCING PATTERN-FORMED RESIN FILM, SEMICONDUCTOR DEVICE, DISPLAY DEVICE, AND METHOD FOR PRODUCING THE SEMICONDUCTOR DEVICE AND THE DISPLAY DEVICE

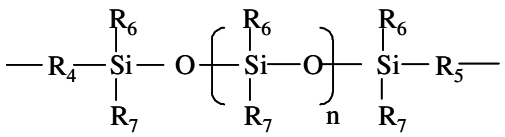
ABSTRACT OF DISCLOSURE

The invention provides a polyamide resin having a structure represented by the formula (1), wherein about 0.1 mol % to about 30 mol % of the total amount of Y in the formula (1) has a structure represented by the formula (2), further a positive-working photosensitive resin composition comprising a diazoquinone compound, a method for producing a pattern-formed resin film using the composition, a semiconductor device and a display device using the composition, and a method for producing the semiconductor device and the display device:



(1)

wherein, X is an organic group of 2 to 4 valences; Y is an organic group of 2 to 6 valences; R_1 is a hydroxyl group or $-O-R_3$ wherein m is an integer of 0 to 2; R_2 is a hydroxyl group, a carboxyl group, $-O-R_3$ or $-COO-R_3$ wherein n is an integer of 0 to 4; R_3 is an organic group having 1 to 15 carbon atoms;



(2)

wherein, each of R_4 and R_5 is a divalent organic group; each of R_6 and R_7 is a monovalent organic group; n is an integer of 0 to 20.

Fig. 1